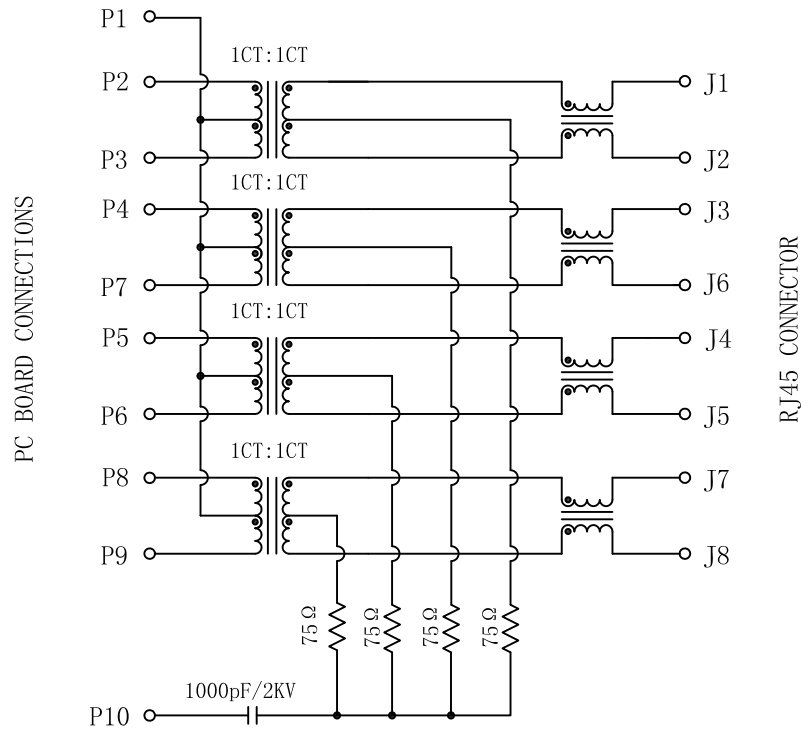


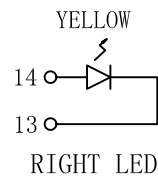
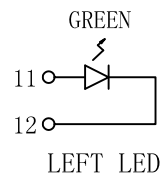
Schematic:

REV.	ECN NO.	DESCRIPTION	DATE	APPD
A	REL			



ELECTRICAL SPECIFICATIONS @25°C

- Turn Ratio($\pm 2\%$):
1CT : 1CT
- Inductance OCL: 350uH MIN
@100KHz/0.1V, 8mA DC Bias
- Insertion Loss:
-1.0dB MAX @ 1.0~65MHz
- Return Loss:
-20dB MIN @ 1~10MHz
-16dB MIN @ 10~30MHz
-12dB MIN @ 30~60MHz
-10dB MIN @ 60~100MHz
- Cross talk:
-40dB MIN @ 1~30MHz
-35dB MIN @ 30~60MHz
-30dB MIN @ 60~100MHz
- Common Mode Rejection:
-30dB MIN @ 1~50MHz
-20dB MIN @ 50~150MHz
- Hipot Test: 1500Vrms MIN
- Operating Temperature Range: 0°C TO 70°C



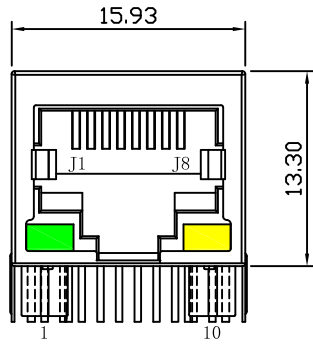
Emitting Color	λ p(nm)	VF@IF=20mA	IR @VR=5V
Green	565	1.8~2.6V	10 μ A max
Yellow	590	1.8~2.6V	10 μ A max



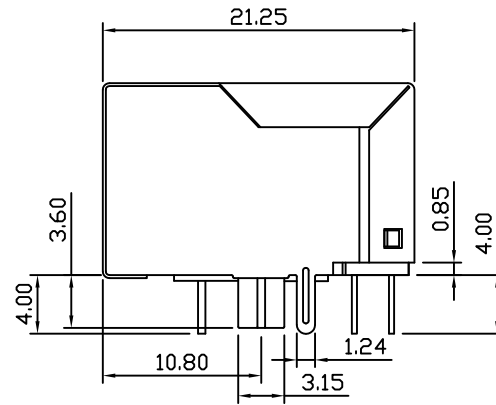
X:X	± 0.30	APPD:	LINK-PP INT'L TECHNOLOGY CO., LIMITED	
X:XX	± 0.25	CHKD:	TITLE: RJ45 Connector with 1000 Base-T Integrated Magnetics	
X:XXX	± 0.05	DR: TOM	PART NO.: LPJG0806HBNL	
ANGLES	$\pm 1^\circ$	UNIT: mm	DWG NO.: LP07111410	
	SCALE: 2/1	SHEET: 1/2	REV: A	

Mechanical:

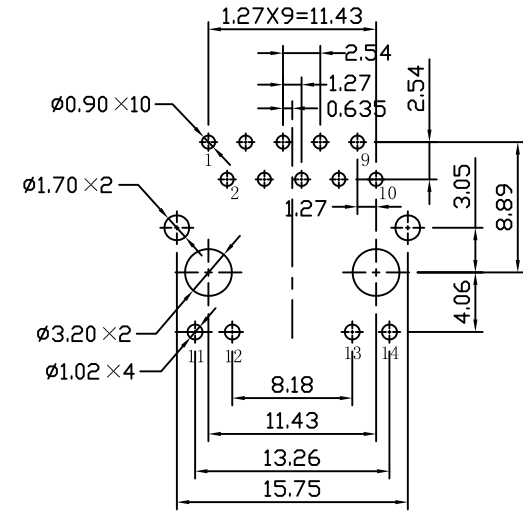
REV.	ECN NO.	DESCRIPTION	DATE	APPD
A	REL		2007-11-14	



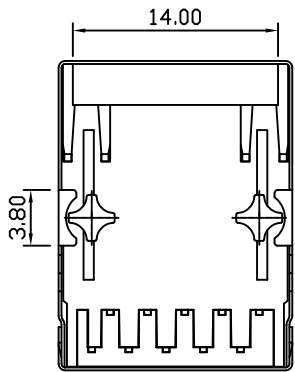
Front Side View



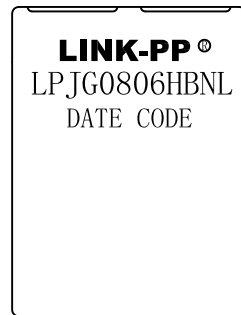
Left Side View



Suggested PCB Layout (Top View)



Bottom Side View



Top Side View



NOTES:

1. Designed to support application, such as SOHO (ADSL modems), LAN-on-Motherboard (LOM), hub and Switches.
2. Designed for PoE, IEEE802.3 applications
3. Power on used or unused pairs for up to 350mADC.
4. Connector Materials:
 Housing: Thermoplastic PBT+30%G.F UL94V-0
 Contact: Phosphor Bronze C5210R-EH Thickness=0.35mm
 Pins: Brass C2680R-H Thickness=0.35mm
 Shield: SUS 201-1/2H Thickness=0.2mm
 Contact plating: Gold 6 micro-inches min. In contact area.
5. Wave solder tip temperature: 265°C Max
 Wave solder tip temperature time: 5 Sec Max

X:X	±0.30	APPD:	LINK-PP INT'L TECHNOLOGY CO., LIMITED	
X:XX	±0.25	CHKD:	TITLE: RJ45 Connector with 1000 Base-T Integrated Magnetics	
X:XXX	±0.05	DR: TOM	PART NO.: LPJG0806HBNL	
ANGLES	±1°	UNIT: mm	DWG NO.: LP07111410	
		SCALE: 2/1	SHEET: 2/2	REV: A